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Vishay Semiconductors

High Power Infrared Emitting Diode, 810 nm, Surface Emitter Technology



DESCRIPTION

As part of the <u>SurfLightTM</u> portfolio, the VSMY98145DS is an infrared, 810 nm emitting diode based on surface emitter technology with high radiant power and high speed, molded in low thermal resistance SMD package with lens. A 42 mil chip provides outstanding radiant intensity and allows DC operation of the device up to 1 A. Superior ESD characteristics are ensured by an integrated Zener diode.

FEATURES

- · Package type: surface mount
- Double stack technology
- Package form: high power QFN with lens
- Dimensions (L x W x H in mm): 3.85 x 3.85 x 2.24
- Peak wavelength: λ_p = 810 nm
- · Zener diode for ESD protection up to 2 kV
- High radiant power
- · High radiant intensity
- Angle of half intensity: $\varphi = \pm 45^{\circ}$
- Designed for high drive currents: up to 1 A (DC) and up to 5 A pulses
- Low thermal resistance: R_{thJA} = 10 K/W
- Floor life: 168 h, MSL 3, according to J-STD-020
- · Lead (Pb)-free reflow soldering
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Infrared illumination for CMOS cameras (CCTV)
- Iris scan
- Machine vision

PRODUCT SUMMARY					
COMPONENT	I _e (mW/sr)	φ (deg)	λ _p (nm)	t _r (ns)	
VSMY98145DS	500	± 45	810	30	

Note

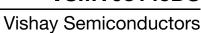
Test conditions see table "Basic Characteristics"

ORDERING INFORMATION					
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM		
VSMY98145DS	Tape and reel	MOQ: 600 pcs, 600 pcs/reel	High power with lens		

Note

· MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)					
PARAMETER	TEST CONDITION	DITION SYMBOL		UNIT	
Reverse voltage		V _R	5	V	
Forward current		I _F	1	А	
Surge forward current	t _p = 10 μs	I _{FSM}	5	А	
Power dissipation		P _V	3.8	W	
Junction temperature		Tj	115	°C	
Operating temperature range		T _{amb}	-40 to +85	°C	
Storage temperature range		T _{stg}	-55 to +100	°C	
Soldering temperature	According to fig. 7, J-STD-20	T _{sd}	260	°C	
Thermal resistance junction / pin	JESD51	R _{thJP}	10	K/W	





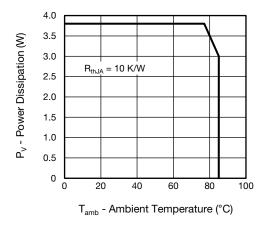


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

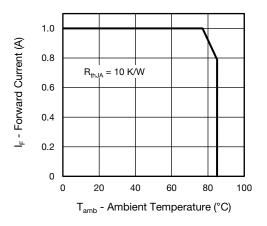


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 1 \text{ A}, t_p = 100 \mu \text{s}$	V_{F}	1	3.3	3.8	V
	$I_F = 2 A, t_p = 100 \mu s$	V_{F}	1	3.5	-	V
Reverse current	$V_R = 5 V$	I _R	ı	-	10	μΑ
Radiant intensity	$I_F = 1 \text{ A}, t_p = 100 \mu \text{s}$	l _e	350	500	-	mW/sr
	$I_F = 2 A, t_p = 100 \mu s$	l _e	1	950	-	mW/sr
Radiant power	$I_F = 1 \text{ A}, t_p = 20 \text{ ms}$	фe	-	1000	-	mW
Angle of half intensity		φ	1	± 45	-	deg
Peak wavelength	I _F = 1 A	λ_{p}	=	810	-	nm
Spectral bandwidth	I _F = 1 A	Δλ	-	50	-	nm
Rise time	I _F = 1 A	t _r	-	30	-	ns
Fall time	I _F = 1 A	t _f	=	30	-	ns

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

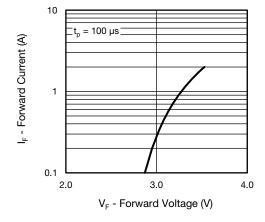


Fig. 3 - Forward Current vs. Forward Voltage

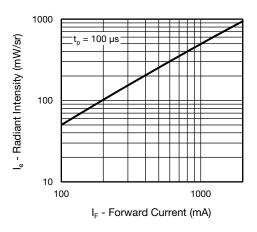
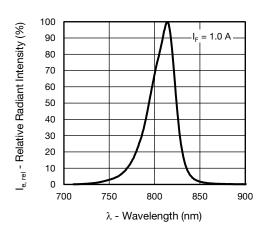
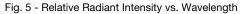


Fig. 4 - Radiant Intensity vs. Forward Current

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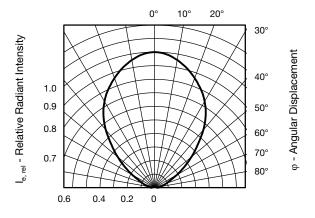
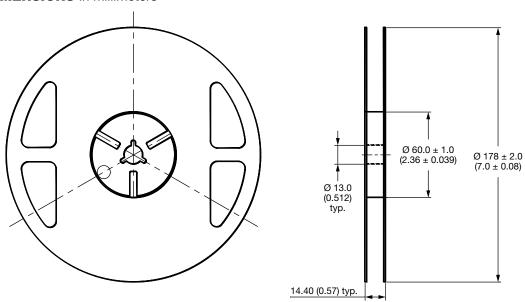


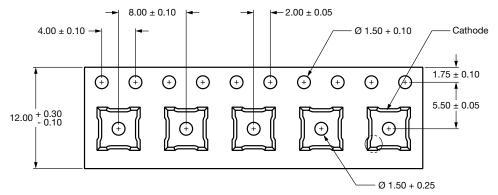
Fig. 6 - Relative Radiant Intensity vs. Angular Displacement

TAPING DIMENSIONS in millimeters



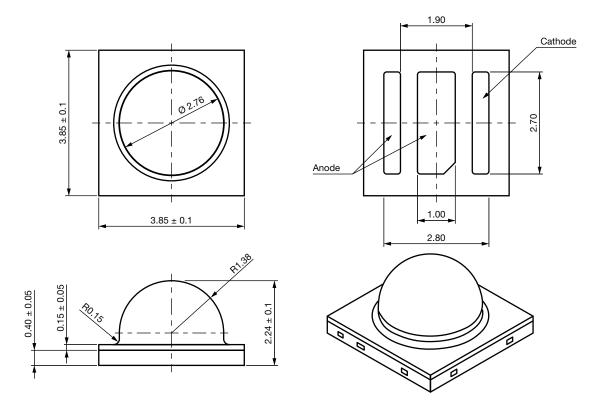
Notes

- Empty component pockets sealed with top cover tape.
- 7 inch reel 600 pieces per reel.
- The maximum number of consecutive missing lamps is two.
- In accordance with ANSI / EIA 481-1-A-1994 specifications.



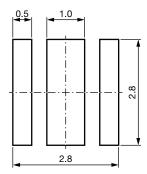
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PACKAGE DIMENSIONS in millimeters



Notes

- Tolerance is ± 0.10 mm (0.004") unless otherwise noted.
- Specifications are subject to change without notice.



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SOLDER PROFILE

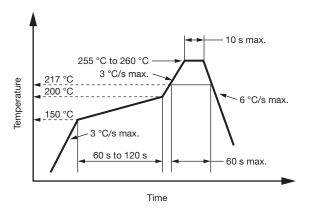


Fig. 7 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 168 h

Conditions: T_{amb} < 30 °C, RH < 60 %

Moisture sensitivity level 3, according to J-STD-020B

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 $^{\circ}$ C (+ 5 $^{\circ}$ C), RH < 5 $^{\circ}$ M.



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